

Enhancement Mode N-Channel Power MOSFET

 $TO-252/NMOS/500V/\pm30V/3V/5A/1.3\Omega$

Rev0.5





Enhancement Mode N-Channel Power MOSFET

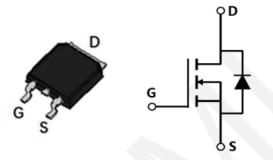
1.Features

- Fast Switching
- ♦ Improved dv/dt Capability

V_{DS} R_{DS(on)} Typ. I_D Max. 500V 1.3Ω @ 10V 5A

2.Applications

- ◆ Load Switch
- PWM Application
- ♦ Power management



3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.	
WP5N50KD	WP5N50	TO-252	2,500	25,000	

4. Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Value	Units
Drain to Source Voltage	V _{DS}	500	V
Gate to Source Voltage	V _{GS}	±30	V
Drain Current (DC)	I _D	5	А
Drain Current (Pulse), PW≤300μs	I _{DP}	17	А
Total Dissipation	P _D	104	W
Avalanche Energy, Single Pulsed	E _{AS}	235	mJ
Junction Temperature	Tj	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5. Thermal Resistance Ratings

Parameter	Symbol	Value	Unit	
Junction to case	R _{eJC}	43	°C/W	
Junction to ambient	R _{0JA}	1	°C/W	

Note 2: When mounted on 1 inch square copper board $t \le 10$ sec The value in any given application depends on the user's specific board design.



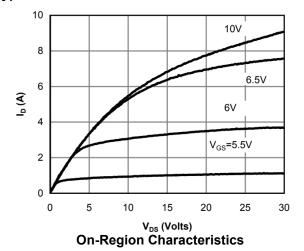
6.Electrical Characteristics at Ta=25°C (Note 3)

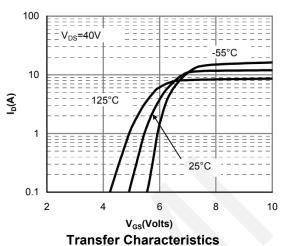
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V _{(BR)DSS}	I _D = 250μA, V _{GS} = 0V	500	535		V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} = 500V, V _{GS} = 0V			1	μΑ
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±30V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _{DS} =250μA	2	3	4	V
Static Drain to Source On-State Resistance	R _{DS(on)}	I _D = 2.5A, V _{GS} = 10V	-	1.3	1.5	Ω
Input Capacitance	C _{iss}	V _{GS} =0V,		538		pF
Output Capacitance	C _{oss}	V _{DS} =25V,		58		pF
Reverse Transfer Capacitance	C _{rss}	Frequency=1.0MHz		4.5		pF
Turn-ON Delay Time	t _{d(on)}			18		ns
Rise Time	t _r	V _{GS} =10V,		32		ns
Turn-OFF Delay Time	t _{d(off)}	$V_{DS} = 250V, I_{D} = 5A,$ $R_{G} = 25\Omega$		34		ns
Fall Time	t _f			22		ns
	Qg	V _{DS} = 450V,		11.5		nC
Total Gate Charge	Q _{gs}	V _{GS} = 10V,		3.8		nC
	Q_{gd}	I _D = 5A		4.1		nC
Diode Forward Voltage	V _{FSD}	I _S = 5A, V _{GS} = 0		0.85	1.2	V

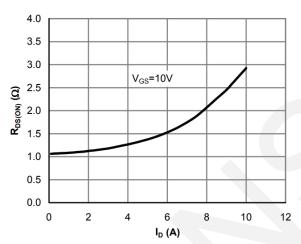
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

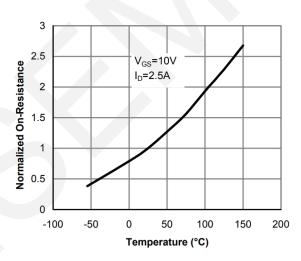


7. Typical electrical and thermal characteristics



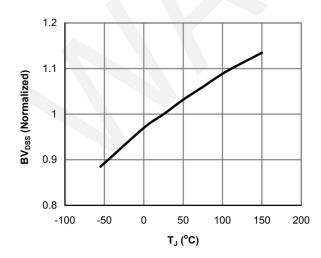


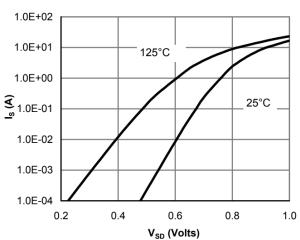




On-Resistance vs. Drain Current and Gate Voltage

On-Resistance vs. Junction Temperature

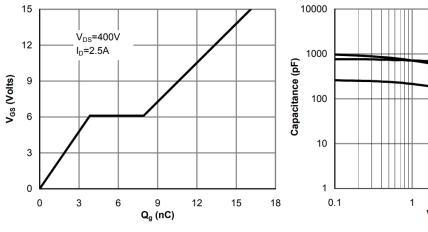


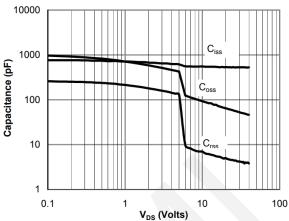


Break Down vs. Junction Temperature

Body-Diode Characteristics

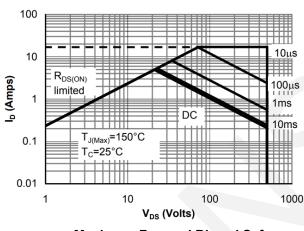


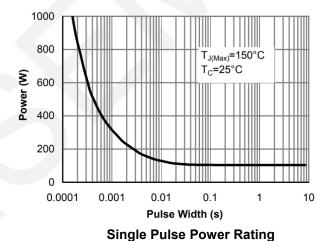




Gate-Charge Characteristics

Capacitance Characteristics



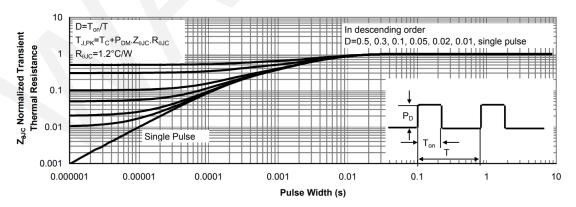


Maximum Forward Biased Safe

Operating Area

•

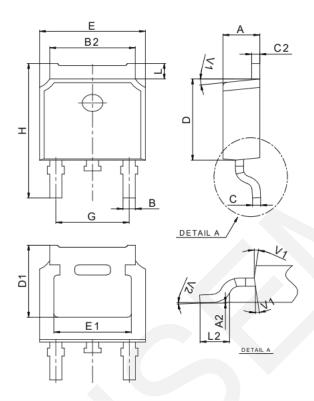
Junction-to-Case



Normalized Maximum Transient Thermal Impedance



8.Package Dimensions



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°



9. Important Notice

WAN SEMICONDUCTOR (NINGBO) CO.,LTD reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services and to discontinue any product or service. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to WANSEMI's terms and conditions of sale supplied at the time of order acknowledgment.

WANSEMI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in WANSEMI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent WANSEMI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

WANSEMI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using WANSEMI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

No WANSEMI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Unless WANSEMI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use, WANSEMI will not be responsible for any failure of such components to meet such requirements.